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Reducing Graphene-Metal Contact Resistance via Laser Nano-welding

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Reducing Graphene-Metal Contact Resistance via Laser Nano-welding

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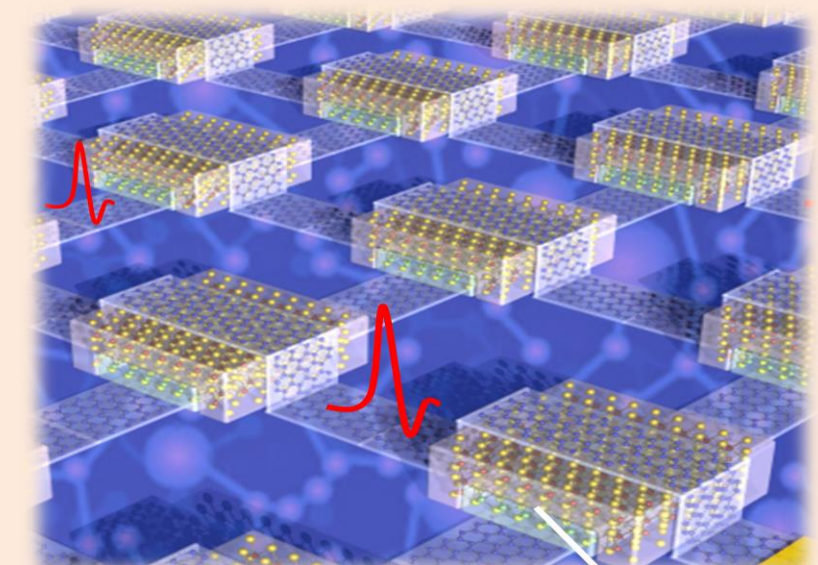
Website: <http://lane.unl.edu>

Laser Assisted Nano-Engineering Lab

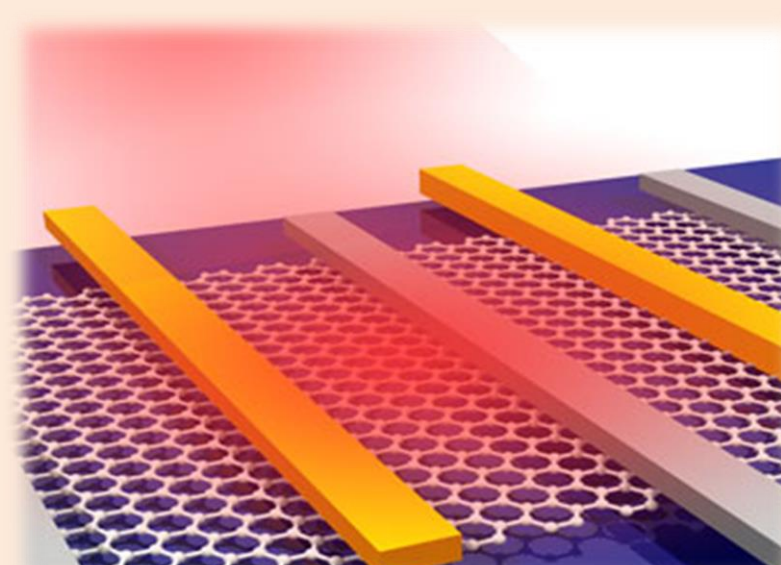
MOTIVATION AND CHALLENGES



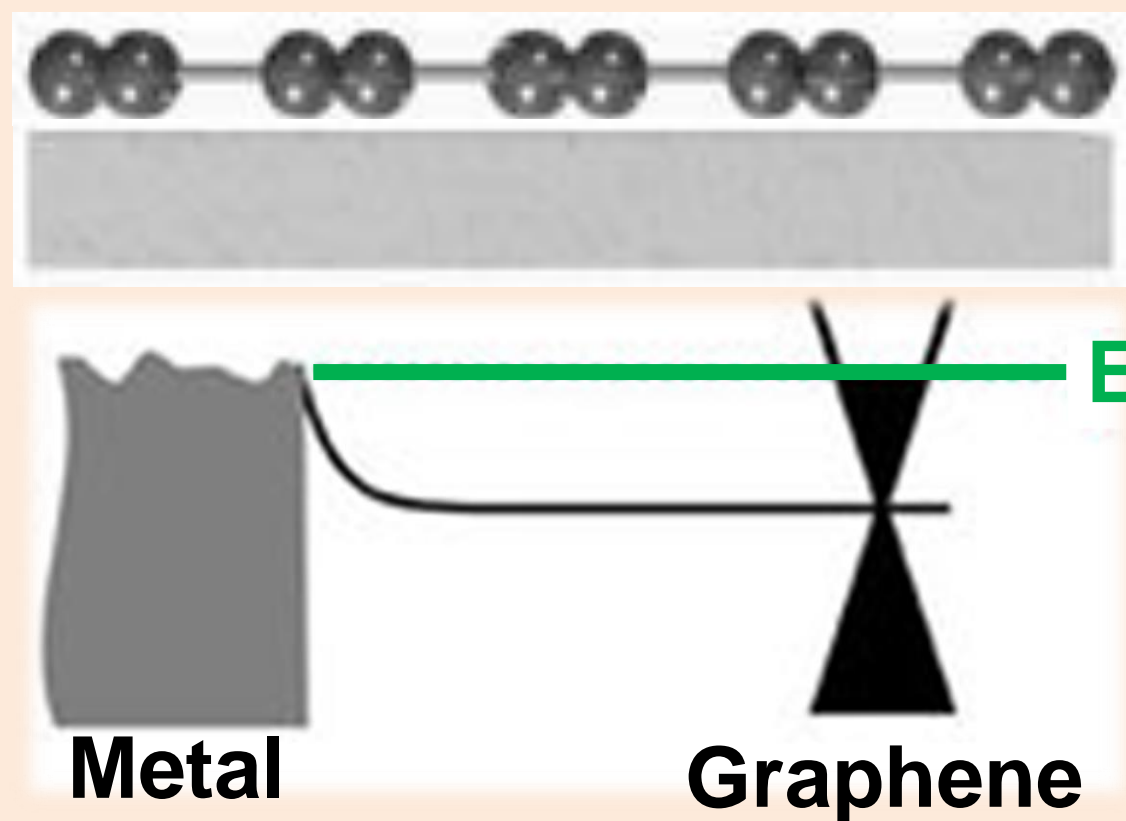
Flexible electronics



Transparent electrodes



Optoelectronics

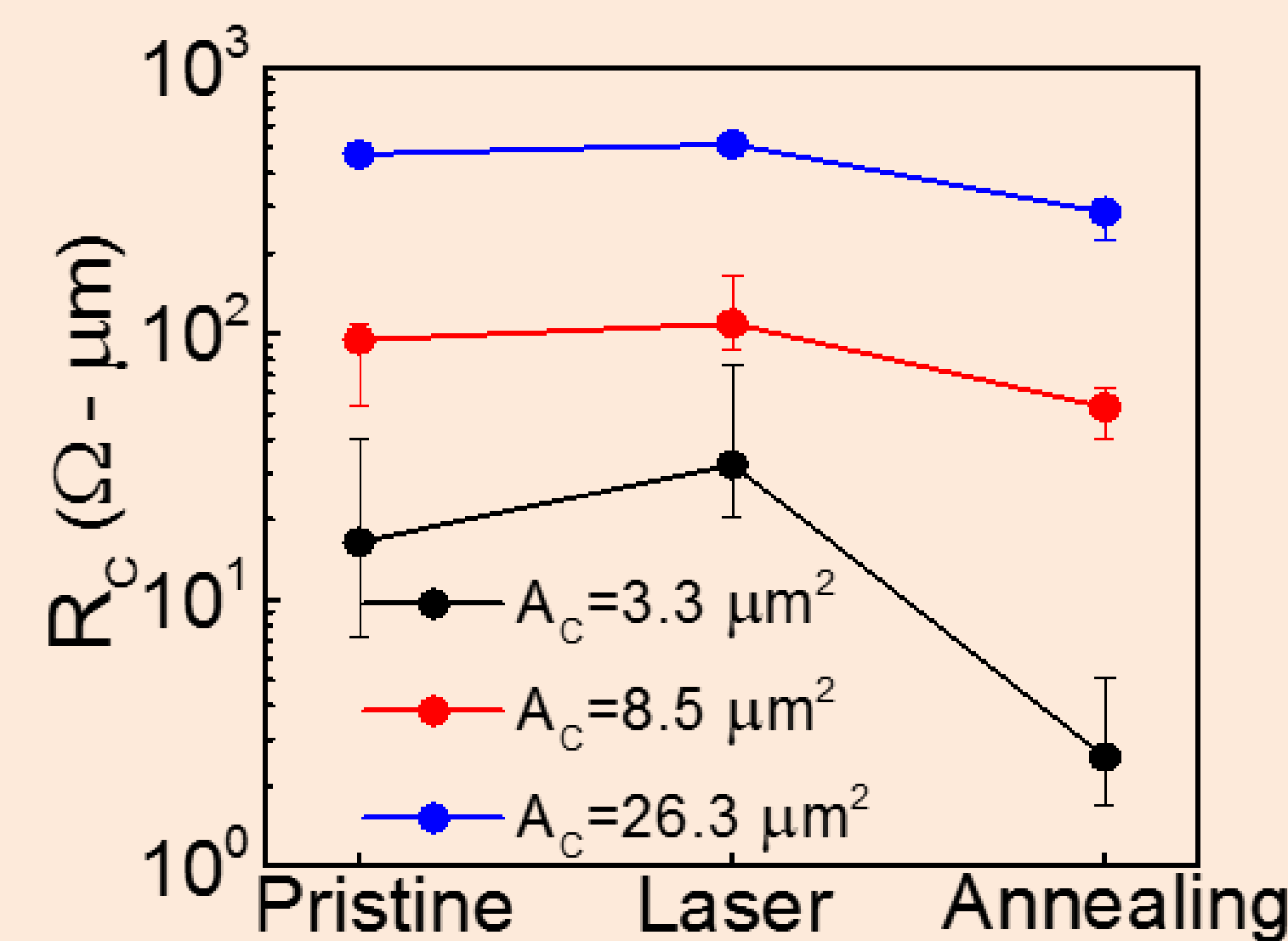


X The large graphene-metal contact resistance is a major limitation for development of graphene electronics.

X graphene behaves as an insulator for out-of-plane carrier transport to metallic contacts.

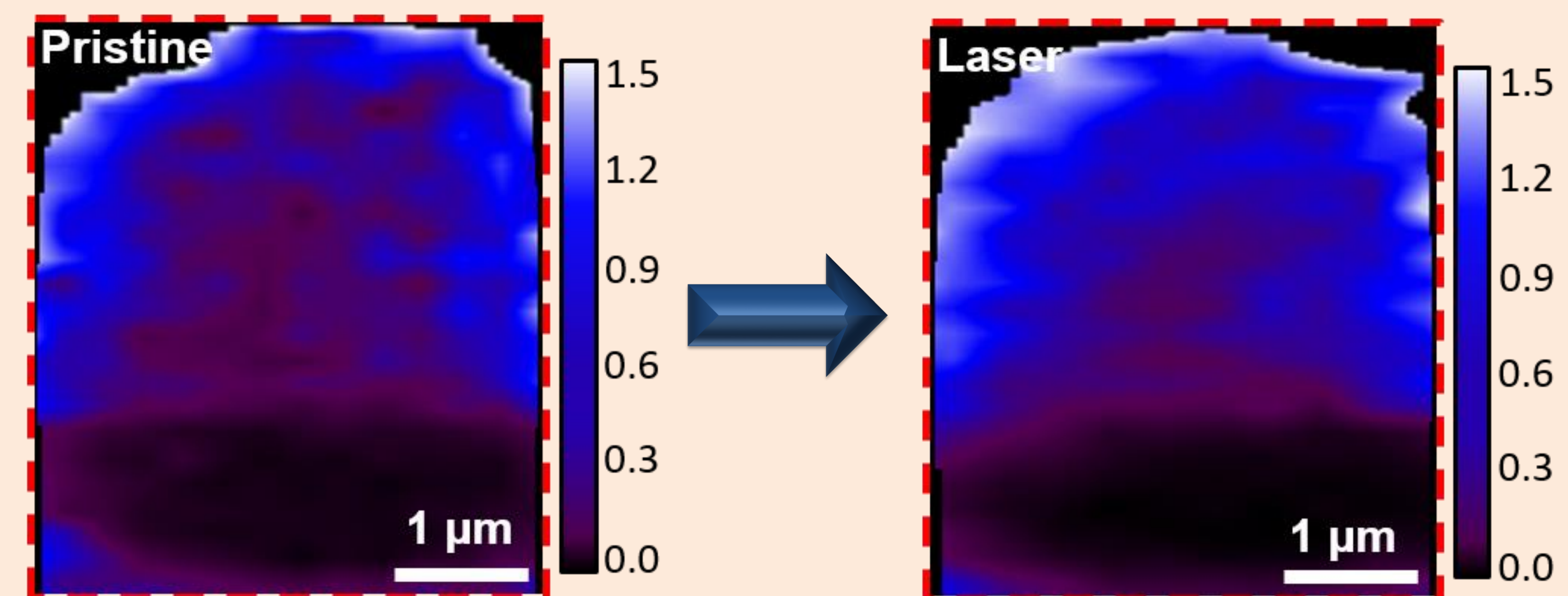
RESULTS AND DISCUSSION

I. Reducing the Contact resistance via laser nano-welding



- Slight increase in R_C for all samples after the laser-irradiation.
- Significant reduction of R_C values after the annealing.
- R_C values as low as $2.57 \Omega \cdot \mu\text{m}$ obtained via laser nano-welding method.

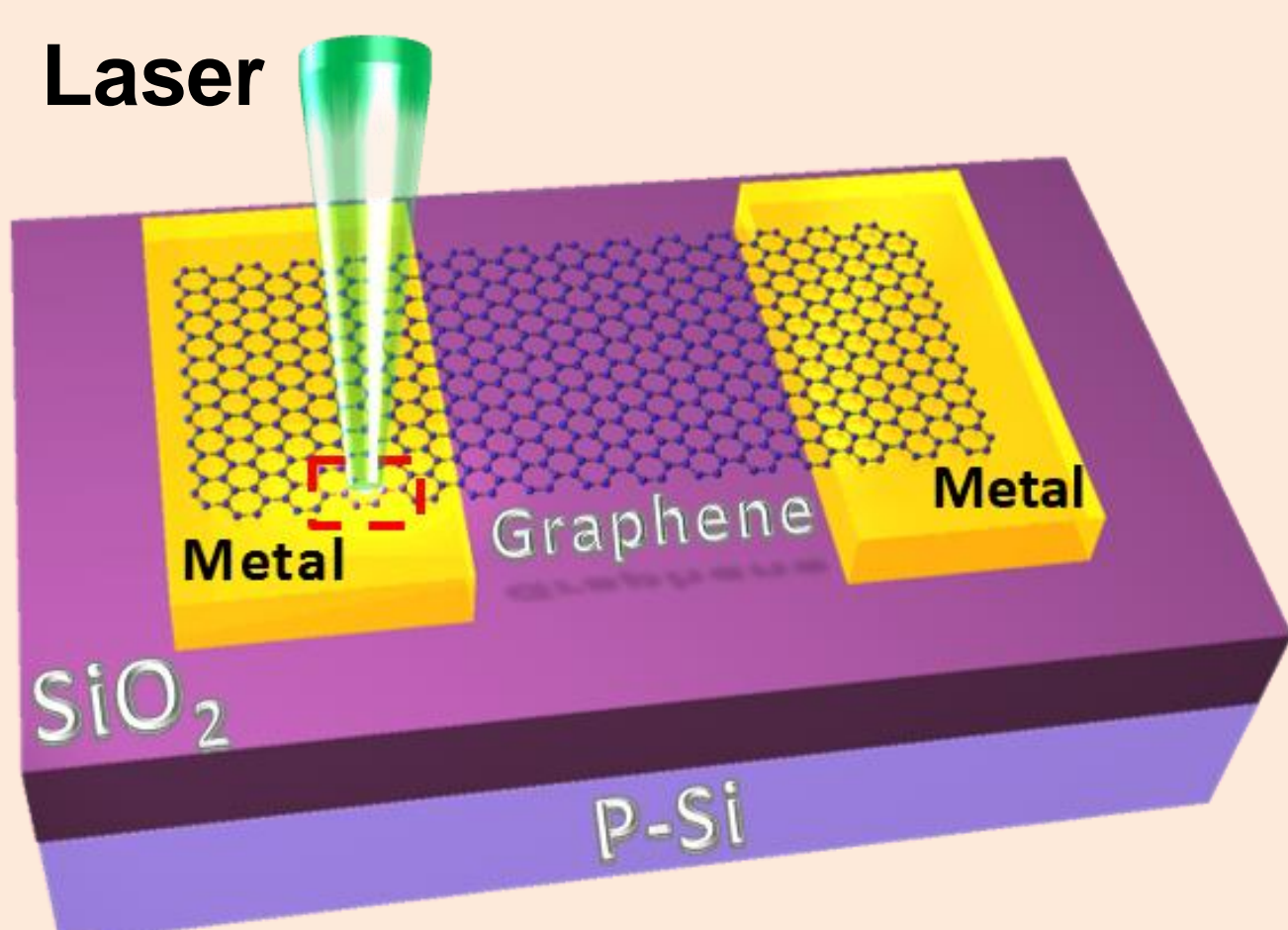
II. Structural characterization using I_D/I_G Raman mapping



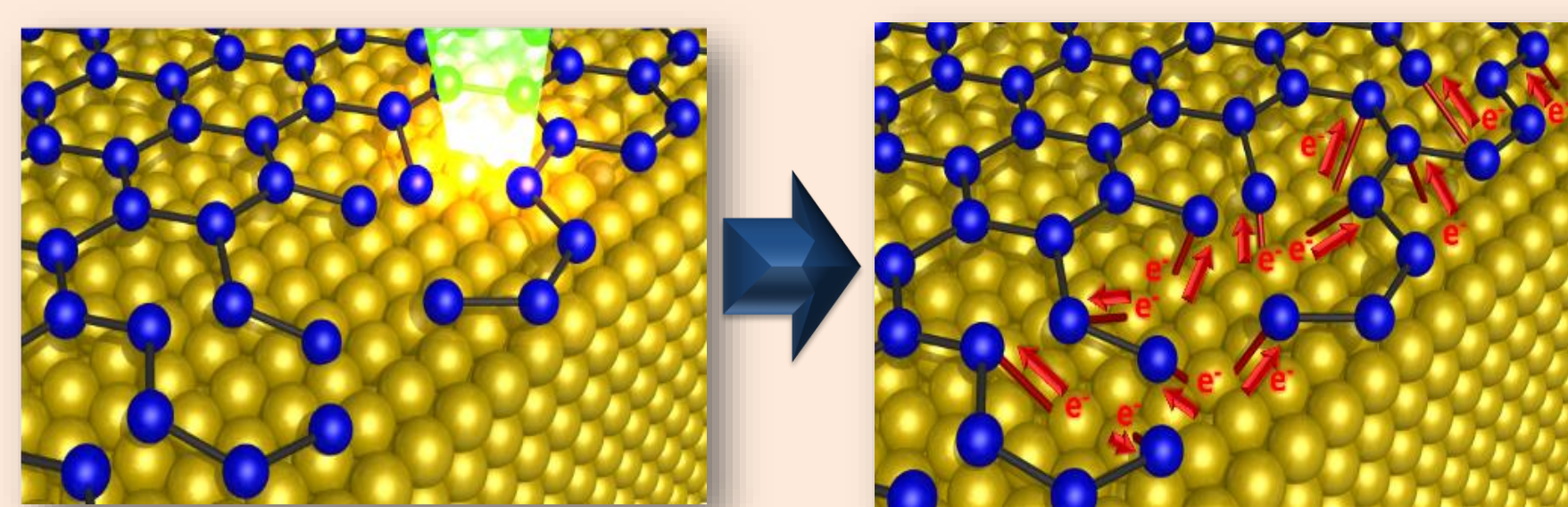
- A rise in the I_D/I_G ratio was observed only at the edges of graphene, where laser irradiation was performed.
- No change was observed at the channel region and the middle of graphene-metal interface.
- Performance degradation was avoided, due to selective mechanism of the laser-irradiation.

PROPOSED SOLUTION

Laser nano-welding of graphene to the metal contacts



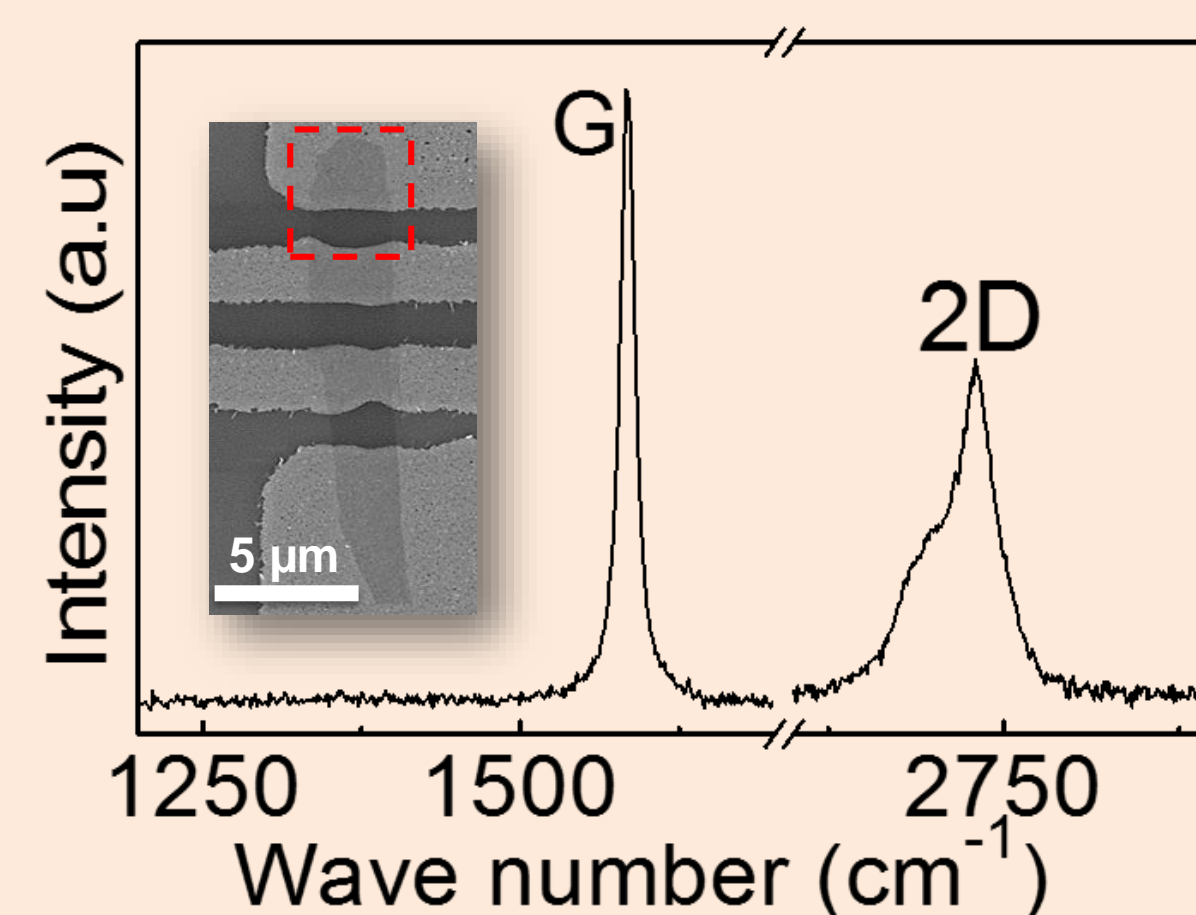
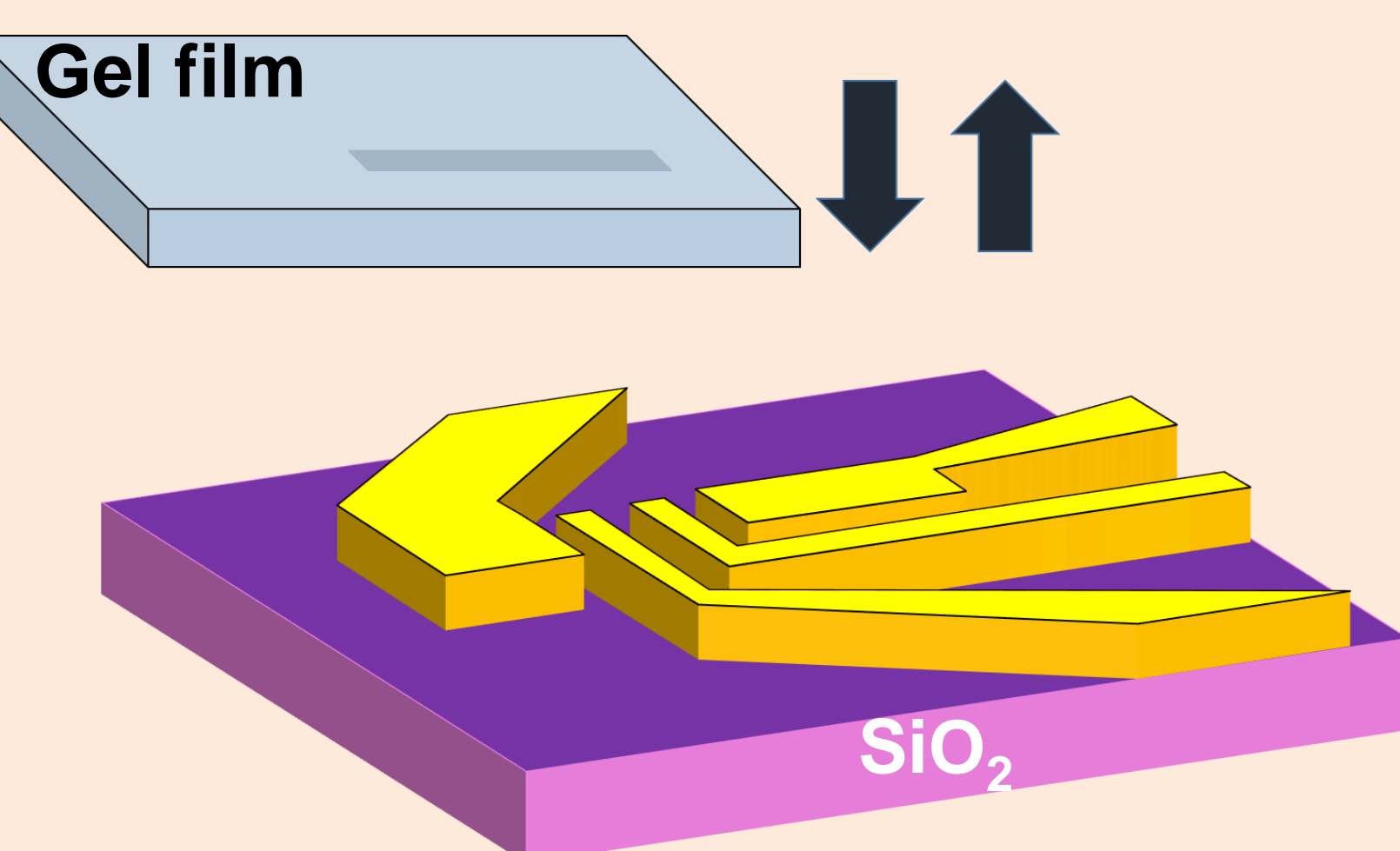
- Laser-induced formation of defects.
- Increase the chemical reactivity of graphene.
- Avoid unwanted damage to channel region.



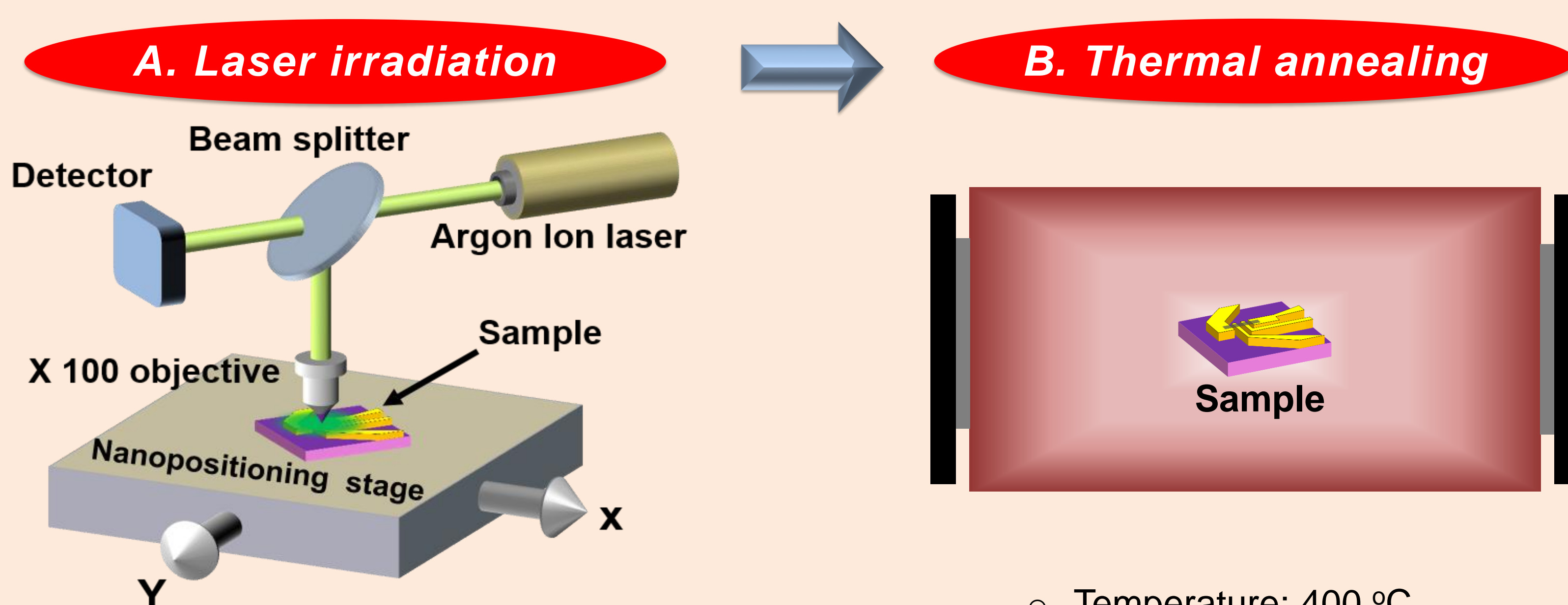
❖ Realization of a strong G-M bonding at laser-induced defects.

METHODS

I. Fabrication of the four-point probe structures



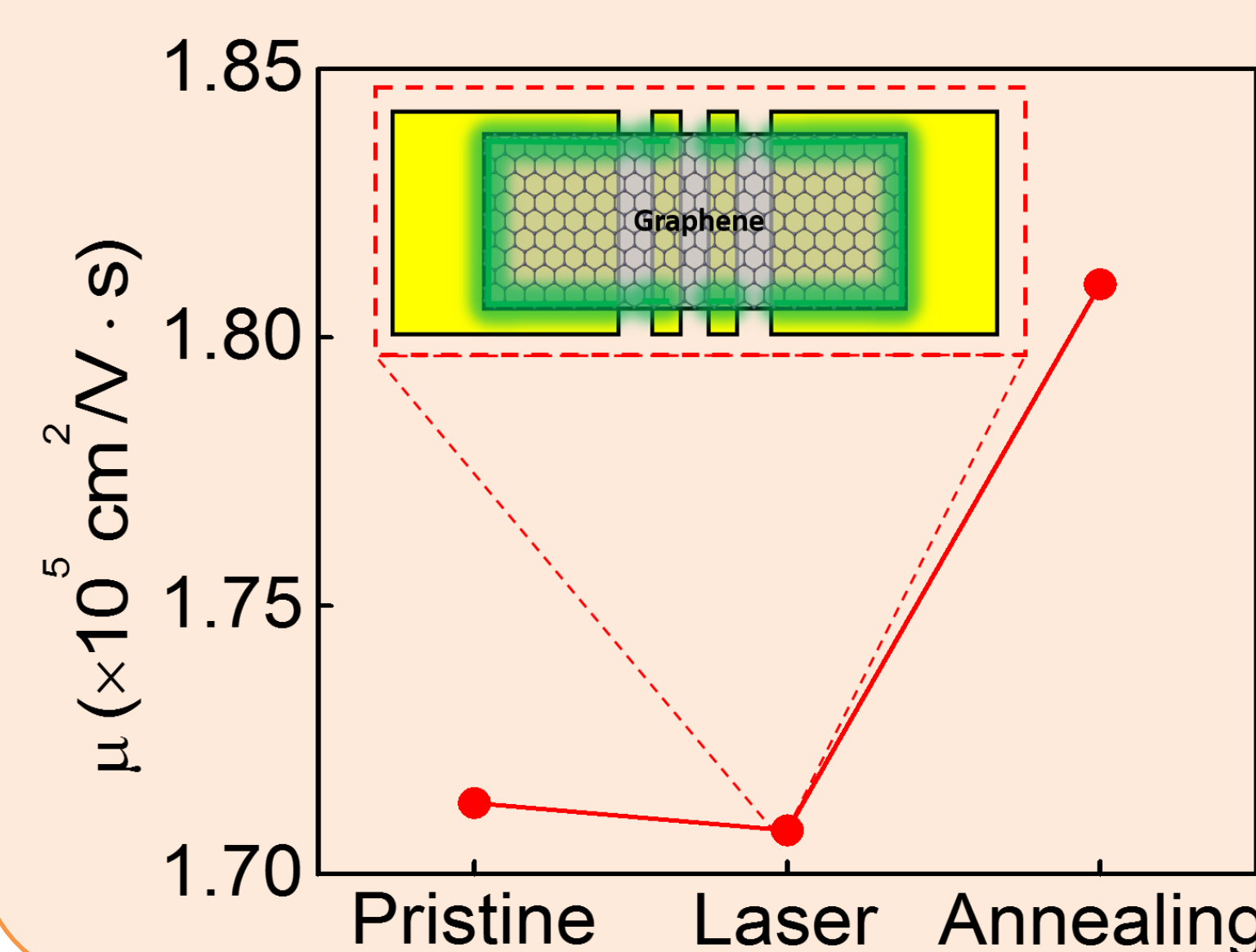
II. Laser nano-welding of graphene



- Wavelength: 514 nm.
- Laser Fluence: $1.6 \times 10^3 \text{ J/cm}^2$.

- Temperature: 400 °C.
- Time: 1 hr.
- Pressure: 1-5 mTorr (Ar purge).

III. Carrier mobility



- Slight reduction in the mobility after the laser irradiation.
- Increased mobility after the thermal annealing.
- Improved carrier injection efficiency, due to the bonding formation at the edges of graphene.

CONCLUSIONS

- ✔ Laser nano-welding was developed and led to R_C reductions of up to **84%**.
- ✔ Localized laser irradiation at the edges of graphene led to the formation of chemically active **point defects**.
- ✔ Precise structural modifications and formation of **G-M bonding** led to improved carrier efficiency in graphene devices.

ACKNOWLEDGEMENTS

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